



Data sheet MTi 1-series

3D AHRS/VRU/IMU module

Document MT0512P, Revision C1, 7 Sep 2016

Features

- Full-featured AHRS on 12.1 x 12.1 mm module
- Roll/pitch accuracy (dynamic) 1.0 deg
- Heading accuracy 2.0 deg
- Minimal requirements on host processor
- Uniform interface over product lifetime
 - No hardware/software interface changes
 - No EOL
- Always best-in-class inertial sensors incorporated
- Industry-leading signal processing pipeline (AttitudeEngine™) with vibration-rejection
- Robust and accurate orientation algorithm (XKF3™)
- API-compatible with all Xsens' Motion Trackers
 - Drivers and examples on ARM® mbed™
- Low power (45 mW @ 3.0V)
- PLCC28-compatible PCB (12.1 x 12.1 x 2.6 mm)

Applications

- Miniature aerial vehicles
- Heavy machinery/agriculture
- Robotics, pedestrian dead-reckoning
- Industrial grade VR/AR, HMD's and handheld devices

Related Resources

- www.xsens.com/MTi-1-series
- MTi 1-series DK User Manual (MT0513P)
- MT Low Level Communication Protocol Documentation (MT0101P)
- MTi White Paper: Next generation Xsens Motion Trackers for Industrial applications

Description

The MTi 1-series is a module outputting 3D orientation, 3D rate of turn, 3D accelerations, and 3D magnetic field, depending on the product configuration. It is available as an Inertial Measurement Unit (IMU), Vertical Reference Unit (VRU) or Attitude and Heading Reference System (AHRS).

This fully-functional self-contained module is easy to design in with limited hardware components to be added. The fully documented, industry-standard communication protocol allows for customization of the data message in terms of data, frequency and output format. Signals are fully processed onboard, requiring very little resources from the host and is well suited for applications in simple MCU-operated environments. The host can read-out the data over SPI, I²C or UART.

With a roll/pitch accuracy of 1.0° RMS and yaw accuracy of 2° RMS under dynamic conditions, the output is excellent for control and stabilization of any object and navigation of e.g. unmanned vehicles.

Product	MTi-1 IMU	MTi-2 VRU	MTi-3 AHRS
Output			
Motion data	•	•	•
Magnetic field	•	•	•
Roll/pitch		•	•
Heading tracking		•	•
Referenced yaw			•

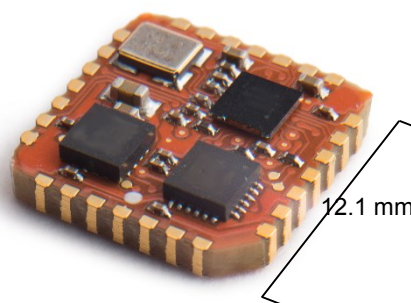


Figure 1: MTi 1-series

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2 General information

2.1 Ordering Information

Part Number	Output	Package	Packing Method
MTI-1-8A7G6T	IMU; inertial data	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-2-8A7G6T	VRU; inertial data, roll/pitch (referenced), yaw (unreferenced)	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-3-8A7G6T	AHRS; inertial data, roll/pitch/yaw	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-1-8A7G6R	IMU; inertial data	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTI-2-8A7G6R	VRU; inertial data, roll/pitch (referenced), yaw (unreferenced)	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTI-3-8A7G6R	AHRS; inertial data, roll/pitch/yaw	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTi-3-8A7G6-DK	Development kit for MTi 1-series, including MTi-3-8A7G6		Single unit

2.2 Block Diagram

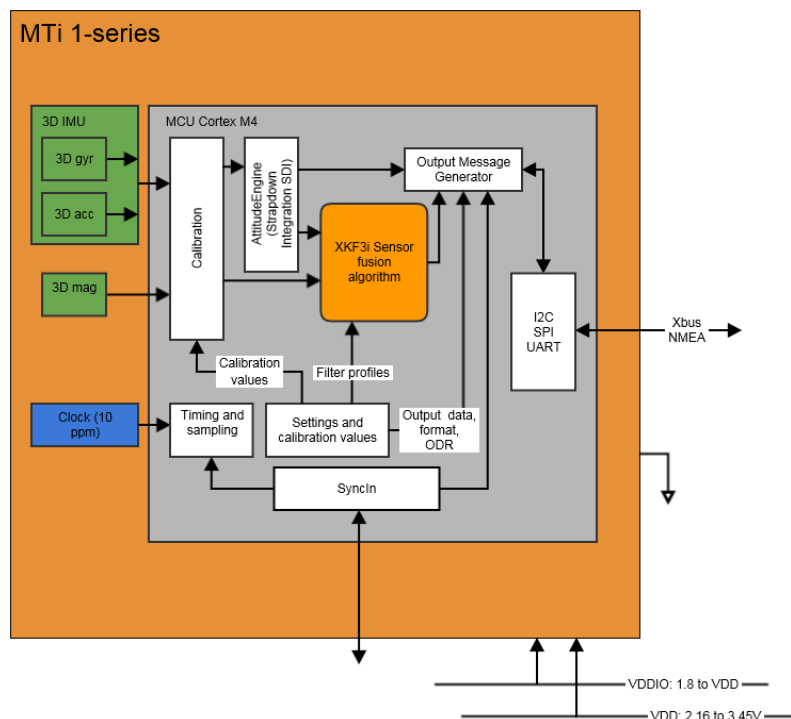


Figure 2: MTi 1-series module block diagram

2.3 Typical Application

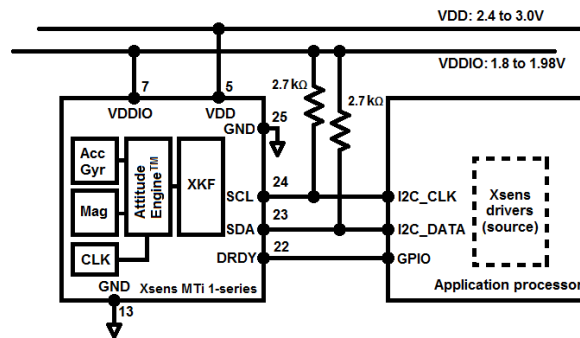


Figure 3: Typical application

2.4 Pin Configuration

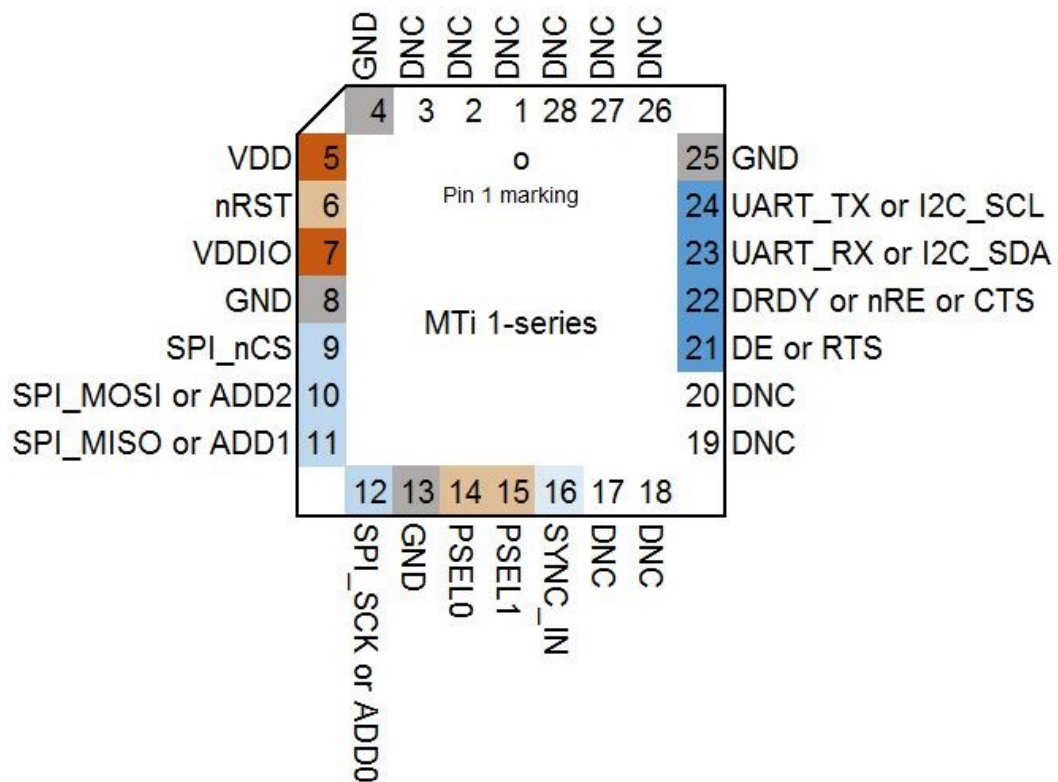


Figure 4: Pin configuration of the MTi 1-series module (top view)

2.5 Pin map

The pin map depends on the peripheral selection. See section 2.7 on how to set the peripherals.

	PSEL: I²C	PSEL: SPI	PSEL: UART half duplex	PSEL: UART full duplex
1	DNC	DNC	DNC	DNC
2	DNC	DNC	DNC	DNC
3	DNC	DNC	DNC	DNC
4	GND	GND	GND	GND
5	VDD	VDD	VDD	VDD
6	nRST	nRST	nRST	nRST
7	VDDIO	VDDIO	VDDIO	VDDIO
8	GND	GND	GND	GND
9	DNC	SPI_NCS	DNC	DNC
10	ADD2 ¹	SPI_MOSI	DNC	DNC
11	ADD1	SPI_MISO	DNC	DNC
12	ADD0	SPI_SCK	DNC	DNC
13	GND	GND	GND	GND
14	PSEL0	PSEL0	PSEL0	PSEL0
15	PSEL1	PSEL1	PSEL1	PSEL1
16	SYNC_IN	SYNC_IN	SYNC_IN	SYNC_IN
17	DNC	DNC	DNC	DNC
18	DNC	DNC	DNC	DNC
19	DNC	DNC	DNC	DNC
20	DNC	DNC	DNC	DNC
21	DNC	DNC	DE	RTS
22	DRDY	DRDY	nRE	CTS ²
23	I2C_SDA	DNC	UART_RX	UART_RX
24	I2C_SCL	DNC	UART_TX	UART_TX
25	GND	GND	GND	GND
26	DNC	DNC	DNC	DNC
27	DNC	DNC	DNC	DNC
28	DNC	DNC	DNC	DNC

¹ I²C addresses, see Table 2: List of I²C addresses

² CTS cannot be left unconnected if the interface is set to UART full duplex. If HW flow control is not used, connect to GND.

2.6 Pin Descriptions

Name	Type	Description
Power Interface		
VDD	Power	Power supply voltage for sensing elements
VDDIO	Power	Digital I/O supply voltage
Controls		
PSEL0	Selection pins	These pins determine the signal interface. See table below. Note that when the PSEL0/PSEL1 is not connected, its value is 1. When PSEL0/PSEL1 is connected to GND, its value is 0
PSEL1		
nRST		Active low reset pin. Only drive with an open drain output or momentary (tactile) switch to GND. During normal operation this pin must be left floating, because this line is also used for internal resets. This pin has an internal weak pull-up to VDDIO.
ADD2	Selection pins	I ² C address selection lines
ADD1		
ADD0		
Signal Interface		
I2C_SDA	I ² C interface	I ² C serial data
I2C_SCL		I ² C serial clock
SPI_nCS	SPI interface	SPI chip select (active low)
SPI_MOSI		SPI serial data input (slave)
SPI_MISO		SPI serial data output (slave)
SPI_SCK		SPI serial clock
RTS	UART interface	Hardware flow control in UART full duplex mode (Ready-to-Send)
CTS		Hardware flow control in UART full duplex mode (Clear-to-Send). If flow control is not used connect to GND
nRE		Receiver control signal in UART half duplex mode
DE		Transmitter control signal in UART half duplex mode
UART_RX		Receiver data input
UART_TX		Transmitter data output
SYNC_IN	Sync interface	SYNC_IN accepts a trigger which sends out the latest available data message
DRDY	Data ready	Data ready pin indicates that data is available (SPI / I ² C)

2.7 Peripheral interface selection

The MTi 1-series modules are designed to be used as a peripheral devices in embedded systems. The module supports universal asynchronous receiver/transmitter (UART), inter-integrated circuit (I²C) and the serial peripheral interface (SPI) protocols. The I²C and SPI protocols are well suited for communications between integrated circuits with on-board peripherals. The MTi 1-series modules have four modes of peripheral interfacing. Only one mode can be used at a time and this is determined by the state of peripheral selection pins PSEL0 and PSEL1 at start up. Table 1 specifies how the PSEL lines select the peripheral interface. Note that the module has internal pull-ups. Not connecting PSEL results in a value of 1, connecting PSEL to a GND results in a value of 0. Examples for communication on embedded systems are available at <https://developer.mbed.org/teams/Xsens>.

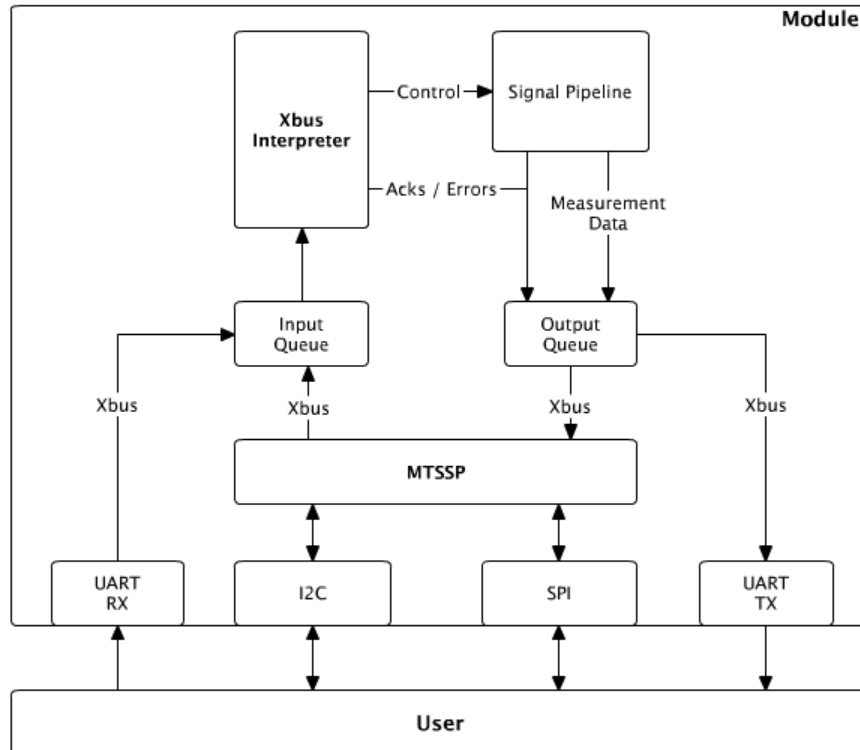
Table 1. Peripheral interface selection

Interface	PSEL0	PSEL1
I ² C	1	1
SPI	0	1
UART half-duplex	1	0
UART full-duplex	0	0

2.7.1 Peripheral Interface Architecture

At its core the module uses the Xsens-proprietary Xbus protocol which is compatible with all Xsens Motion Tracker products. This protocol is available on all interfaces, UART (asynchronous serial port interfaces) and I²C and SPI buses. The I²C and SPI buses differ from UART in that they are synchronous and have a master-slave relation in which the slave cannot send data by itself. This makes the Xbus protocol not directly transferable to these buses. For this purpose, the MTSSP protocol is introduced a protocol for exchanging standard Xbus protocol messages over the I²C and SPI buses.

The diagram below shows how MTSSP is fitted in the module's (simplified) communication architecture. The module has generic Input- and Output-Queues for Xbus protocol messages. For I²C and SPI, these messages are translated by the MTSSP layer. For the UART connection these messages are transported as-is.



2.7.2 Xbus Protocol

The Xbus protocol is Xsens' proprietary protocol that allows straightforward interfacing with the MTi 1-series. Information about the Xbus protocol can be found in the Low-Level Communication Protocol Documentation. Section 7 provides a short introduction on the Xbus protocol. It is advised to read [this short introduction](#) first before proceeding to the MTSSP explanation.

2.7.3 MTSSP Synchronous Serial Protocol

This communication protocol used for both I²C and SPI is called MTSSP (MTi Synchronous Serial Protocol). It is also implemented in the ARM® mbed™ example program (see <https://developer.mbed.org/teams/Xsens>)

Data flow

MTSSP communication happens according the master-slave model. The MTi 1-series module will always fulfill the slave-role while the user/integrator of the module is always the Master.

Communication is always initiated and driven by the Master; The Master either writes data to the module or the Master reads data from the module. The Master sends messages to the module in order to control it. These messages are reduced Xbus messages. A reduced Xbus message is equal to a normal Xbus message with the exception that preamble and busId are removed to save bandwidth. The calculation of the checksum is done by assuming a busId value of 0xFF (master device).

The module needs time to process the control messages it receives and will generate an acknowledge message when ready. In order to get these acknowledge messages at the Master the Master needs to read them.

The following diagram shows data flow between Master and module:

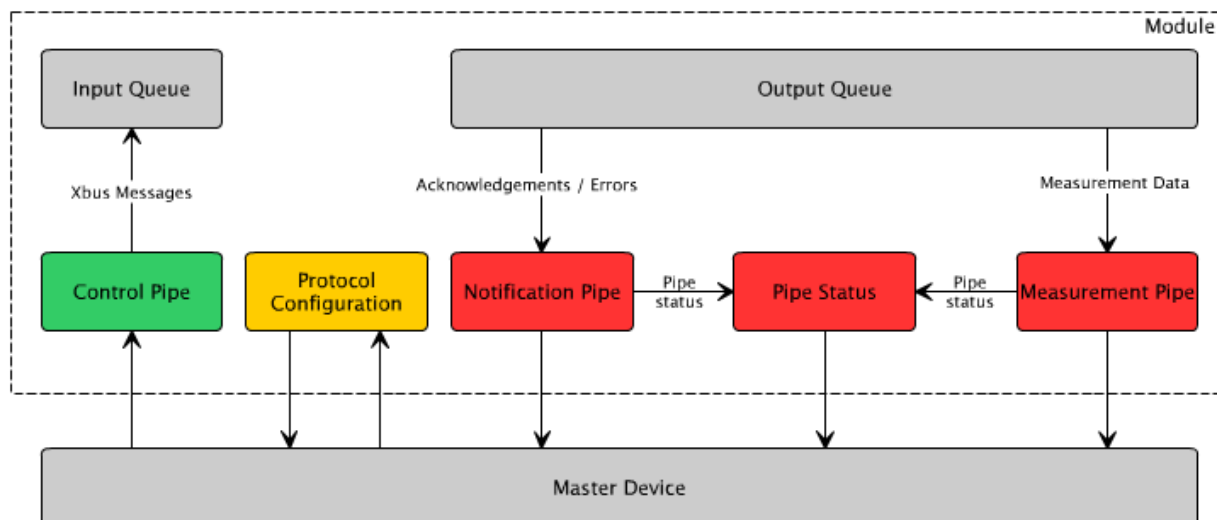


Figure 6: Data flows within MTSSP

Data ready signal

The Data Ready Signal (DRDY) is a notification line driven by the module. Its default behavior is to indicate the availability of new data in either the notification- or the measurement pipe. By default, the line is idle low and will go high when either pipe contains an item. When both pipes are empty the DRDY line will go low again. The Master can change the behavior of the DRDY signal.

The polarity can be changed to idle high, the output type can be switched between push-pull and open drain. The state of a specific pipe can be ignored. For example, it can be configured that the presence of data in the notification pipe won't influence the state of the DRDY pin.

Opcodes

The following opcodes are defined:

Opcode	Name	Read/Write	Description
0x01	ProtocolInfo	Read	Status of the protocol behaviour, protocol version
0x02	ConfigureProtocol	Write	Tweak the Protocol, e.g. the behaviour of the DRDY pin, behaviour of the pipes
0x03	ControlPipe	Write	Used to send control messages to the module
0x04	PipeStatus	Read	Provides status information for the read pipes
0x05	NotificationPipe	Read	Used to read non-measurement data: errors acknowledgements and other notifications from the module
0x06	MeasurementPipe	Read	All measurement data generated by the module will be available in the measurement pipe

ProtocolInfo (0x01)

The ProtocolInfo opcode allows the Master to read the active protocol configuration. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspInfo
{
    uint8_t m_version;
    uint8_t m_drdyConfig;
};
```

m_version

7	6	5	4	3	2	1	0
VERSION [7:0]							

m_drdyConfig

Bits 7:4	Reserved for future use
Bit 3	MEVENT : Measurement pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 2	NEVENT : Notification pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 1	OTYPE : Output type of DRDY pin 0: Push/pull 1: Open drain
Bit 0	POL : Polarity of DRDY signal 0: Idle low 1: Idle high

ConfigureProtocol (0x02)

The ProtocolInfo opcode allows the Master to change the active protocol configuration. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspConfiguration
{
    uint8_t m_drdyConfig;
};
```

m_drdyConfig

Bits 7:4	Reserved for future use
Bit 3	MEVENT : Measurement pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 2	NEVENT : Notification pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 1	OTYPE : Output type of DRDY pin 0: Push/pull 1: Open drain
Bit 0	POL : Polarity of DRDY signal 0: Idle high 1: Idle low

ControlPipe (0x03)

The ControlPipe opcode allows the Master to write messages to the control pipe. The bytes following the opcode are interpreted as a single (reduced) Xbus message

PipeStatus (0x04)

The PipeStatus opcode allows the Master to retrieve the status of the module's Notification- and Measurement pipes. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspConfiguration
{
    uint16_t m_notificationMessageSize;
    uint16_t m_measurementMessageSize;
};
```

NotificationPipe (0x05)

The NotificationPipe opcode is used to read from the notification pipe. The read data is a single reduced Xbus message

MeasurementPipe (0x06)

The MeasurementPipe opcode is used to read from the measurement pipe. The read data is a single reduced Xbus message

2.7.4 I²C

The MTi 1-series supports the I²C transport layer as of firmware 1.0.6. Note that devices with firmware revision 1.0.3 and lower cannot be upgraded to support this protocol.

The MTi 1-series module acts as an **I²C Slave**. The Master is defined as the user of the MTi 1-series module.

The I²C slave address is determined by the ADD0, ADD1 and ADD2 pins. These pins are pulled-up internally so when left unconnected the address selection defaults to ADD[0..2] = 111.

Note: when the module is in the Development Kit, the I²C address connections cannot be left unconnected.

Table 2. List of I²C addresses

I ² C address	ADD0	ADD1	ADD2
0x1D	0	0	0
0x1E	1	0	0
0x28	0	1	0
0x29	1	1	0
0x68	0	0	1
0x69	1	0	1
0x6A	0	1	1
0x6B (default)	1	1	1

Table 3. Implemented I²C bus protocol features

Feature	Slave Requirement	MTi 1-series
7-bit slave address	Mandatory	Yes
10-bit slave address	Optional	No
Acknowledge	Mandatory	Yes
Arbitration	N/A	N/A
Clock stretching	Optional	Yes ³
Device ID	Optional	No
General Call address	Optional	No
Software Reset	Optional	No
START byte	N/A	N/A
START condition	Mandatory	Yes
STOP condition	Mandatory	Yes
Synchronization	N/A	N/A

Writing to the module

Write operations consists of a single I²C write transfer. The Master addresses the MTi 1-series and the first byte that is sent is interpreted by the module as the opcode. The following bytes are considered the actual message. The actual handling of the received message by the module is determined by the opcode.

The maximum message size a module can receive is 512 bytes. If the Master sends more than 512 bytes the module will reset its receive-buffer which reduces the received message to consist only of the excess bytes.

³ The MTi-1 module relies on the I²C clock stretching feature to overcome fluctuations in processing time, the Master is required to support this feature

The following diagram shows the write message operation:

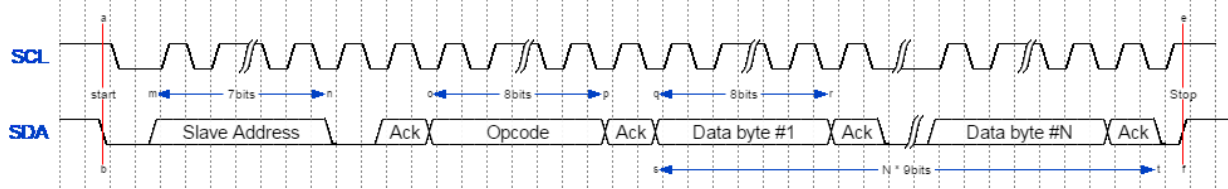


Figure 7: I²C write message operation

Reading from the module

Reading from the module should start by first writing an opcode that tells the module what the Master needs to read.

Based on the opcode the module will prepare the related data to be transmitted. The Master then can do an I²C read transfer to retrieve the data. Starting the read transfer after the opcode write can also be done using a repeated start condition as is shown in the diagram below.

It is up to the Master to determine how many bytes need to be read. The Master should use the PipeStatus (0x04) opcode of the MTSSP protocol for this.

If the master reads more bytes than necessary the MTi 1-series will restart sending the requested data from the beginning.

The following diagram shows a read message transfer using a repeated start:

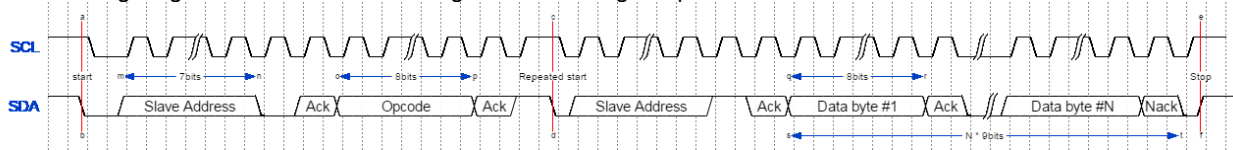


Figure 8: Read message transfer using a repeated start (I²C)

The following diagram shows a read message transfer using a full write transfer for the opcode followed by a read transfer to get the data:

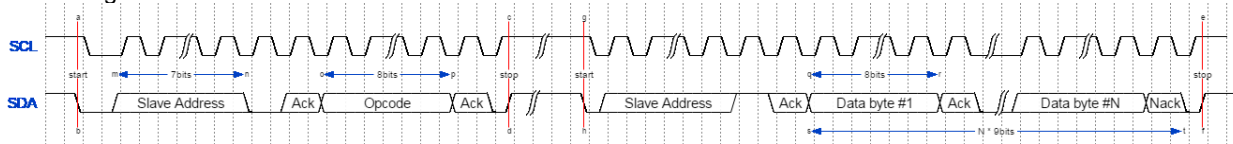


Figure 9: Full write transfer and full read transfer (I²C)

2.7.5 SPI

The MTi 1-series supports the SPI transport layer as of firmware 1.0.6. Note that devices with firmware revision 1.0.3 and lower cannot be upgraded to support this protocol.

The MTi 1-series module acts as an **SPI Slave**. The Master is defined as the user of the MTi 1-series module.

SPI Configuration

The MTi 1-series supports 4-wire mode SPI. The four lines used are:

- Chipselect (SPI_nCS)
- Serial Clock (SPI_SCK)
- Master data in, slave data out (SPI_MISO)
- Master data out, slave data in (SPI_MOSI)

The module uses SPI mode 3; Data is captured on the rising clock edge and data is latched/propagated on the falling clock edge. (CPOL=1 and CPHA=1);

Data is clocked-out MSB first. The module uses an 8-bit data format

Data transfer

There is a single type of SPI transfer used for all communications. The diagram below shows the basic transfer.

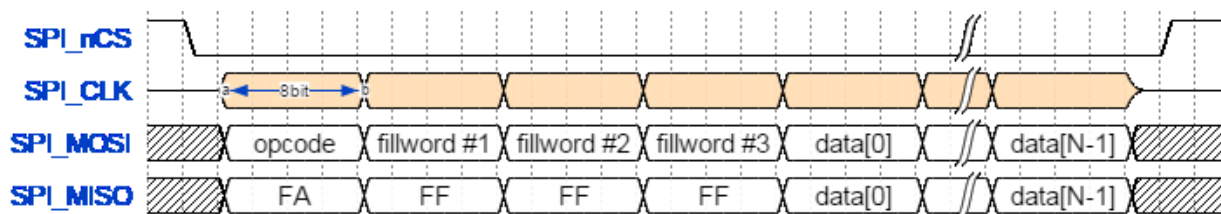


Figure 10: SPI basic transfer

A transfer is started selecting the Slave by pulling the SPI_nCS low. The SPI_nCS line is to be kept low for the duration of the transfer. The Slave will interpret the rising edge of the SPI_nCS line as the end of the transfer. The Master places the data it needs to transmit on the SPI_MOSI line. The Slave will place its data on the SPI_MISO line.

The first byte transmitted by the Master is the opcode which identifies what kind of data is transmitted by the Master and what kind of data the Master wants to read from the Slave (See MTSSP).

The second- to fourth byte transmitted are the fill words. These fill words are needed to give the Slave some time to prepare the remainder of the transfer. In principal the Slave is free to choose the value of the fill word; and its value should therefore be ignored by the Master. However the first 4 bytes transmitted by the MTi 1-series module are always 0xFA, 0xFF, 0xFF, 0xFF.

Following the first four words are the actual data of the transfer. It is the responsibility of the Master to determine how many bytes need to be transferred. The Master should use the PipeStatus (0x04) opcode of the MTSSP protocol for this.

Timing

The following timing constraints apply to the SPI transport layer.

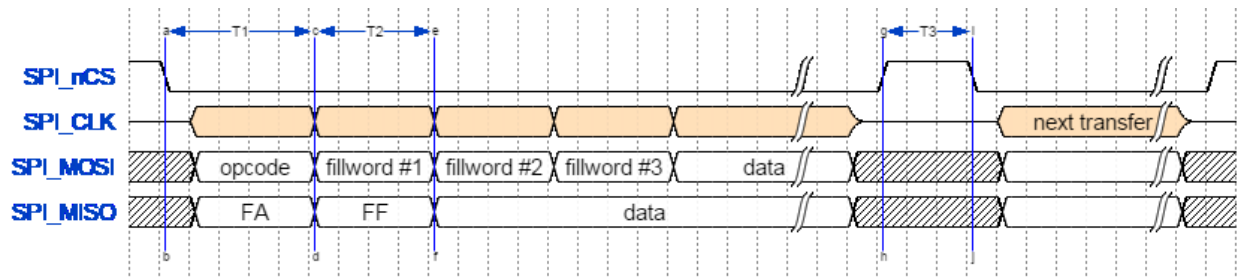


Figure 11: SPI timing

Symbol	Parameter	Conditions	Unit	Min	Typ	Max
T1	Slave select to first complete word delay		μs	4		
T2	Byte time		μs	4		
T3	Consecutive SPI transfer guard time		μs	3		
	Max SPI bitrate		Mbit			2

2.7.6 UART half duplex

The MTi 1-series module can be configured to communicate over UART in half duplex mode. The UART frame configuration is 8 data bits, no parity and 1 stop bit (8N1). In addition to the RX and TX pins the control lines nRE and DE are used. These control outputs are used to drive the TX signal on a shared medium and to drive the signal of the shared medium on the RX signal.

A typical use case for this mode is to directly drive a RS485 transceiver where the shared medium is the RS485 signal and nRE and DE lines control the buffers inside the transceiver.

When the MTi is transmitting data on its TX pin it will raise both the nRE and DE lines, else it will pull these lines low.

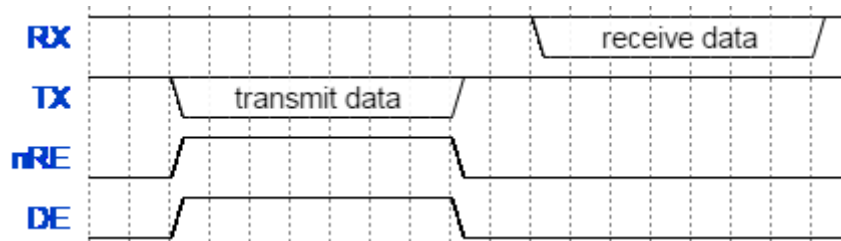


Figure 12 Behaviour of the nRE and DE lines

Note that in this mode the UART of the MTi 1-series itself is still operating full duplex.

2.7.7 UART full duplex with RTS/CTS flow control

The MTi 1-series module can be configured to communicate over UART in full duplex mode with RTS/CTS flow control. The UART frame configuration is 8 data bits, no parity and 1 stop bit (8N1). In addition to the RX and TX signals for data communication the RTS and CTS signals are used for hardware flow control.

The CTS signal is an input for the MTi. The MTi checks the state of the CTS line at the start of every byte it transmits. If CTS is low the byte will be transmitted. Otherwise transmission is postponed until CTS is lowered. When during the transmission of a byte the CTS signal is raised then the transmission of that byte is completed before postponing further output. This byte will not be retransmitted. This behaviour is shown in the following image:

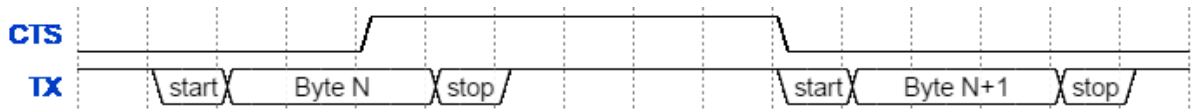


Figure 13 Data transmit behaviour under CTS

The RTS signal is an output for the MTi. If the RTS line is high, the MTi is busy and unable to receive new data. Otherwise the MTi-1 series UART is idle and ready to receive. After receiving a byte the DMA controller of the MTi will transfer the byte to its receive FIFO. The RTS signal will be asserted during this transfer. So with every byte received the RTS line is raised shortly like shown in the following image:

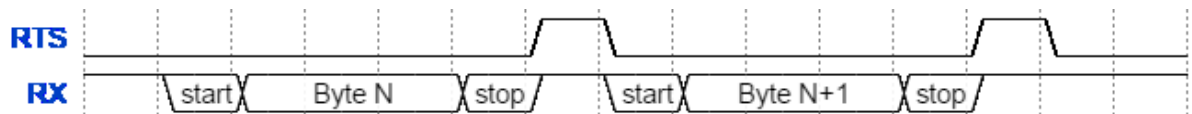


Figure 14 RTS behaviour under data reception

This communication mode can be used without hardware flow control. In this case the CTS line needs to be tied low (GND) to make the MTi transmit.

2.8 Recommended external components

Component	Description	Typical value
R_{pu}	I ² C pull-up resistor	2.7 k Ω

Notes:

- R_{pu} is only needed when the MTi-1 is configured for I²C interface
- R_{PSEL} is only required when interface is not I²C.

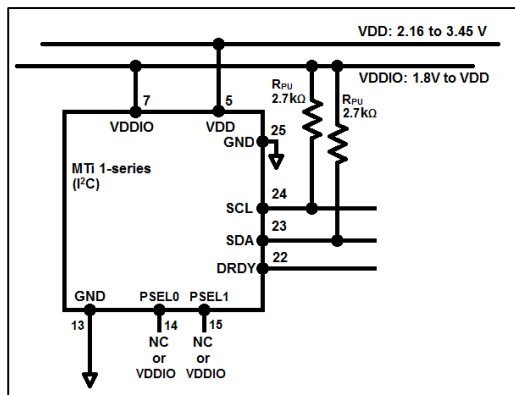


Figure 15: External components (I²C interface)

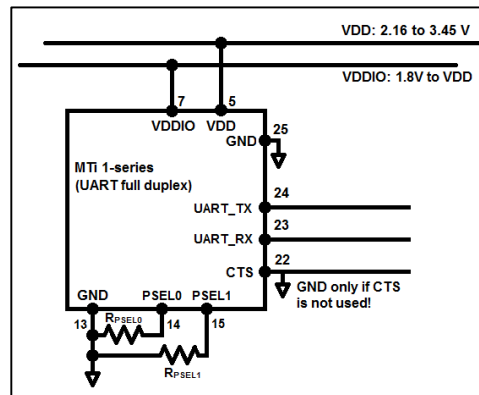


Figure 16: External components (UART interface)

3 MTi 1-series architecture

This section discusses the MTi 1-series architecture including the various configurations and the signal processing pipeline.

3.1 MTi 1-series configurations

The MTi 1-series is a fully-tested self-contained module that can output 3D orientation data (Euler angles (roll, pitch, yaw), rotation matrix (DCM) and quaternions), orientation and velocity increments (Δq and Δv) and sensors data (acceleration, rate of turn, magnetic field). The MTi 1-series module is available as an Inertial Measurement Unit (IMU), Vertical Reference Unit (VRU) and Attitude and Heading Reference System (AHRS). Depending on the product, output options may be limited to sensors data and/or unreferenced yaw.

All MTi's feature a 3D accelerometer/gyroscope combo-sensor, a magnetometer, a high-accuracy crystal and a low-power MCU. The MCU coordinates the synchronization and timing of the various sensors, it applies calibration models (e.g. temperature models) and output settings and runs the sensor fusion algorithm. The MCU also generates output messages according to the proprietary XBus communication protocol. The messages and the data output are fully configurable, so that the MTi 1-series limits the load, and thus power consumption, on the application processor.

3.1.1 MTi-1 IMU

The MTi-1 module is an Inertial Measurement Unit (IMU) that outputs 3D rate of turn, 3D acceleration and 3D magnetic field. The MTi-1 also outputs coning and sculling compensated orientation increments and velocity increments (Δq and Δv) from its AttitudeEngine™. Advantages over a gyroscope-accelerometer combo-sensor are the inclusion of synchronized magnetic field data, on-board signal processing and the easy-to-use communication protocol. Moreover, the testing and calibration over temperature performed by Xsens result in a robust and reliable sensor module, that can be integrated within a short time frame. The signal processing pipeline and the suite of output options allow access to the highest possible accuracy at any output data rate, limiting the load on the application processor.

3.1.2 MTi-2 VRU

The MTi-2 is a 3D vertical reference unit (VRU). Its orientation algorithm (XKF3™) outputs 3D orientation data with respect to a gravity referenced frame: drift-free roll, pitch and unreferenced yaw. In addition, it outputs calibrated sensor data: 3D acceleration, 3D rate of turn and 3D magnetic field data. All modules of the MTi 1-series are also capable of outputting data generated by the strapdown integration algorithm (the AttitudeEngine™ outputting orientation and velocity increments Δq and Δv). The 3D acceleration is also available as so-called free acceleration which has gravity subtracted. Although the yaw is unreferenced, though still superior to gyroscope integration. With the feature Active Heading Stabilization (AHS, see section 8.2) the drift in unreferenced yaw can be limited to 1 deg after 60 minutes, even in magnetically disturbed environments.

3.1.3 MTi-3 AHRS

The MTi-3 supports all features of the MTi-1 and MTi-2, and in addition is a full gyro-enhanced Attitude and Heading Reference System (AHRS). It outputs drift-free roll, pitch and true/magnetic North referenced yaw and sensors data: 3D acceleration, 3D rate of turn, as well as 3D orientation and velocity increments (Δq and Δv), and 3D earth-magnetic field data. Free acceleration is also available for the MTi-3 AHRS.

3.2 Signal processing pipeline

The MTi 1-series is a self-contained module, so all calculations and processes such as sampling, coning and sculling compensation and the Xsens XKF3™ sensor fusion algorithm run on board.

3.2.1 Strapdown integration

The Xsens optimized strapdown algorithm (AttitudeEngine™) performs high-speed dead-reckoning calculations at 1 kHz allowing accurate capture of high frequency motions. This approach ensures a high bandwidth. Orientation and velocity increments are calculated with full coning and sculling compensation. At an output data rate of up to 100 Hz, no information is lost, yet the output data rate can be configured low enough for systems with limited communication bandwidth. These orientation and velocity increments are suitable for any 3D motion tracking algorithm. Increments are internally time-synchronized with the magnetometer data.

3.2.2 XKF3™ Sensor Fusion Algorithm

XKF3 is a sensor fusion algorithm, based on Extended Kalman Filter framework that uses 3D inertial sensor data (orientation and velocity increments) and 3D magnetometer, also known as '9D' to optimally estimate 3D orientation with respect to an Earth fixed frame.

XKF3 takes the orientation and velocity increments together with the magnetic field updates and fuses this to produce a stable orientation (roll, pitch and yaw) with respect to the earth fixed frame.

The XKF3 sensor fusion algorithm can be processed with filter profiles. These filter profiles contain predefined filter parameter settings suitable for different user application scenarios. All filter profiles can be used with Active Heading Stabilization (AHS), which significantly reduces heading drift during magnetic disturbances. See also section 8.2.

The following filter profiles are available:

- **General** – suitable for most applications. Supported by the MTi-3 module.
- **Dynamic** – assumes that the motion is highly dynamic. Supported by the MTi-3 module.
- **High_mag_dep** – heading corrections rely on the magnetic field measured. To be used when magnetic field is homogeneous. Supported by the MTi-3 module.
- **North_reference** – assumes a good MFM and a homogeneous mag field. Given stable initialization procedures and observability of the gyro bias, after dynamics this filter profile will trust more on the gyro solution and the heading will slowly converge to the disturbed mag field over the course of time. Supported by the MTi-3 module.
- **VRU_general** – Roll and pitch are referenced to the vertical (gravity), yaw is determined by dead-reckoning. Consider using VRU_general in environments that have a heavily disturbed magnetic field. The VRU_general filter profile is the only filter profile available for the MTi-2-VRU, also supported by the MTi-3 module

3.2.3 Frames of reference used in MTi 1-series

The MTi 1-series module uses a right-handed coordinate system as the basis of the sensor of frame.

The following data is outputted in corresponding reference coordinate systems:

Data	Symbol	Reference coordinate system
Acceleration	a_x, a_y, a_z	Sensor-fixed
Rate of turn	$\omega_x, \omega_y, \omega_z$	Sensor-fixed
Magnetic field	m_x, m_y, m_z	Sensor-fixed
Free acceleration	a_x, a_y, a_z	Local Tangent Plane (LTP), default ENU
Velocity increment	$\Delta v_x, \Delta v_y, \Delta v_z$	Local Tangent Plane (LTP), default ENU
Orientation increment	$\Delta q_0, \Delta q_1, \Delta q_2, \Delta q_3$	Local Tangent Plane (LTP), default ENU
Orientation	Euler angles, quaternions or rotation matrix	Local Tangent Plane (LTP), default ENU

Local Tangent Plane (LTP) is a local linearization of the Ellipsoidal Coordinates (Latitude, Longitude, Altitude) in the WGS-84 Ellipsoid.

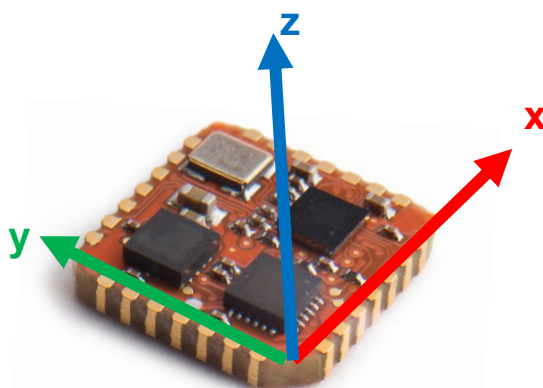


Figure 17: Default sensor fixed coordinate system for the MTi 1-series module

It is straightforward to apply a rotation matrix to the MTi, so that the velocity and orientation increments, free acceleration and the orientation output is output using that coordinate frame. The default reference coordinate system is East-North-Up (ENU) and the MTi 1-series has predefined output options for North-East-Down (NED) and North-West-Up (NWU). Any arbitrary alignment can be entered. These orientation resets have effect on all outputs that are by default outputted with an ENU reference coordinate system.

4 3D Orientation and performance specifications

4.1 3D Orientation specifications

Table 4. Orientation specifications

	Parameter	Typ	Unit	Comments
Roll/pitch	Static	0.75	deg	
	Dynamic	1.0	deg	
Yaw (heading)	Static/dynamic, Magnetic field referenced	2.0	deg	MTi-3 AHRS only in a homogenous magnetic field and a filter profile using magnetic field as reference.
	VRU_general filter profile (unreferenced yaw)	<1	deg after 60 min	Active Heading Stabilization (AHS) feature. See section 8.2 for more information.
	Output data rate	0-100	Hz	Accuracy and latency independent of output data rate. Output data rate may be any integer divider of 100 Hz or may be triggered by an external pulse (SYNC_IN)

4.2 Sensors specifications⁴

Table 5. Gyroscope specifications

Parameter	Min	Typ	Max	Unit	Comments
Full range	±2000			deg/s	
Non-linearity		0.1		% of FS	
Sensitivity variation		0.05		%	Over temperature range
Noise density		0.01		%s/√Hz	
g-sensitivity		0.001		deg/s/g	
In-run bias stability		10		deg/h	
Bias repeatability (1 yr)		0.5		deg/s	The bias is continuously estimated by XKF3i.
Bandwidth		180		Hz	
Natural frequency		26		kHz	This is the resonating frequency of the mass in the gyro.
Output date rate			1000	Hz	RateOfTurnHR DataID only; RateOfTurn DataID and velocity increments up to 100 Hz

Table 6. Accelerometers specifications

Parameter	Min	Typ	Max	Unit	Comments
Full range	±16			g	
Non-linearity		0.5		% of FS	
Sensitivity variation		0.05		%	Over temperature range
Noise density		200		μg/√Hz	
Zero g-output		±2		mg	
In-run bias stability		0.1		mg	
Bandwidth		180		Hz	
Output data rate			1000	Hz	AccelerationHR DataID only; Acceleration DataID and orientation increments up to 100 Hz

⁴ As Xsens continues to update the sensors on the module, these specifications may change

Table 7. Magnetometer specifications

Parameter	Min	Typ	Max	Unit	Comments
Full range	±0.8			Gauss	Magnetic fields above 0.8 Gauss are not used in XKF3. Actual full range is ±1.9 Gauss
Non-linearity		0.1		% of FS	
Noise density		200		µG/√Hz	

Table 8. Alignment specifications

Parameter	Typ	Unit	Comments
Non-orthogonality (accelerometer)	0.05	deg	
Non-orthogonality (gyroscope)	0.05	deg	
Non-orthogonality (magnetometer)	0.05	deg	
Alignment (gyr to acc)	0.05	deg	
Alignment (mag to acc)	0.1	deg	
Alignment of acc to the module board	0.2	deg	

5 Sensor calibration

Each MTi is individually calibrated and tested over its temperature range. The (simplified) sensor model of the gyroscopes, accelerometers and magnetometers can be represented as following:

$$s = K_T^{-1}(u - b_T)$$

- s = sensor data of the gyroscopes, accelerometers and magnetometers in rad/s, m/s² or a.u. respectively
- K_T^{-1} = gain and misalignment matrix (temperature compensated)
- u = sensor value before calibration (unsigned 16-bit integers from the sensor)
- b_T = bias (temperature compensated)

Xsens' calibration procedure calibrates for many parameters, including bias (offset), alignment of the sensors with respect to the module PCB and each other and gain (scale factor). All calibration values are temperature dependent and temperature calibrated. The calibration values are stored in non-volatile memory in the MTi.

6 System and electrical specifications

6.1 Interface specifications

Table 9. Communication interfaces

Interface		Min	Typ	Max	Units
I ² C	Host I ² C interface speed			400	kHz
SPI	Host SPI Interface Speed			2	MHz
	Clock Duty Cycle	30	50	70	%
UART	Baud Rates		921.6	4000	kbps

Table 10. Auxiliary interfaces

Interface		Min	Max	Unit	Comments
SYNC_IN	V _{IL}		0.3 * VDDIO	V	Digital input voltage
	V _{IH}	0.45 * VDDIO + 0.3		V	Digital input voltage
	V _{HYS}	0.45 * VDDIO + 0.3		V	
nRST	V _{IL}		0.3 * VDDIO	V	Only drive momentarily
	R _{PU}	30	50	kΩ	Pull-up resistor
	Generated reset pulse duration	20		μs	

6.2 System specifications

Table 11. System specifications

Interface		Min	Typ	Max	Comments	
Size	Width/Length	12.0	12.1	12.2	mm	PLCC-28 compatible
	Height	2.45	2.55	2.65	mm	
Weight			0.66		gram	
Temperature	Operating temperature	-40		+85	°C	Ambient temperature, non-condensing
	Specified performance operating temperature	0		+60	°C	
Power consumption			44		mW	VDD 3.0V; VDDIO 1.8V
Timing accuracy			10		ppm	
MTBF		225,000			hours	

6.3 Electrical specifications

Table 12. Electrical specifications

	Min	Typ	Max	Unit	Comments
VDD	2.16		3.45	V	
VDD noise			50	mVpp	
VDDIO	1.8		VDD	V	
V _{IL}			0.3 * VDDIO	V	Digital input voltage
V _{IH}	0.45 * VDDIO + 0.3			V	Digital input voltage
V _{HYS}	0.45 * VDDIO + 0.3			V	Digital input voltage
V _{OL}			0.4	V	Digital output voltage
V _{OH}	VDDIO – 0.4			V	Digital output voltage

6.4 Absolute maximum ratings

	Min	Max	Unit	Comments
Storage temperature	-40	+125	°C	
Operating temperature	-40	+85	°C	
VDD	0.3	4.0	V	
VDDIO	0.3	VDD + 0.5	V	
Acceleration ⁵		10,000	g	Any axis, unpowered, for 0.2 ms
ESD protection ⁶		±2000	V	Human body model

6.5 Compliance

All Xsens products, including The MTi 1-series modules and DK are RoHS compliant. The MTi 1-series modules are CE/FCC certified.

⁵  This is a mechanical shock (g) sensitive device. Proper handling is required to prevent damage to the part.

⁶  This is an ESD-sensitive device. Proper handling is required to prevent damage to the part.

7 MTi 1-series settings and outputs

The MTi 1-series module uses the Xsens-proprietary Xbus protocol, which is compatible with all Xsens Motion Tracker products.

7.1 Message structure

The communication with the MT is done by messages which are built according to a standard structure. The message has two basic structures; one with a standard length and one with extended length. The standard length message has a maximum of 254 data bytes and is used most frequently. In some cases the extended length message needs to be used if the number of data bytes exceeds 254 bytes.

An MT message (standard length) contains the following fields:

Xbus header				DATA	CHECKSUM
Preamble	BID	MID	LEN		

An MT message (extended length) contains these fields:

Preamble	BID	MID	LEN ^{ext}	LEN	DATA	CHECKSUM
----------	-----	-----	--------------------	-----	------	----------

Field	Field width	Description
Preamble	1 byte	Indicator of start of packet → 250 (0xFA)
BID	1 byte	Bus identifier or Address → 255 (0xFF)
MID	1 byte	Message identifier
LEN	1 byte	For standard length message: Value equals number of bytes in DATA field. Maximum value is 254 (0xFE) For extended length message: Field value is always 255 (0xFF)
EXT LEN	2 bytes	16 bit value representing the number of data bytes for extended length messages. Maximum value is 2048 (0x0800)
IND ID	1 byte	The type of indication received
DATA (standard length)	0 – 254 bytes	Data bytes (optional)
DATA (extended length)	255 – 2048 bytes	Data bytes
Checksum	1 byte	Checksum of message

Details on the Xbus protocol message structure can be found in the MT Low Level Communication Protocol documentation (LLCP).

7.2 Output settings

The section below only describes the most important set of MTData2 data messages. For all messages supported by the MTi 1-series, refer to the MT Low Level Communication Protocol documentation (LLCP).

The Output Configuration message sets the output of the device. Each data message has a DataID which consists of a data type and a number format. The table below shows the most important MTData2 Data identifiers. The message SetOutputconfiguration holds the DataID and the output frequency.

SetOutputConfiguration

MID 192 (0xC0)

DATA OutputConfig (N*4 bytes)

Set the output configuration of the device.

The data is a list of maximum 32 data identifiers combined with a desired output frequency. The response message contains a list with the same format, but with the values actually used by the device. Each entry in the list contains:

Offset	Value
0	Data Identifier (2 bytes)
2	Output frequency (2 bytes)

Group Name	Type Name	XDA type name ⁷	Hex Value
Timestamp		XDI_TimestampGroup	
	Packet Counter	XDI_PacketCounter	1020
	Sample Time Fine	XDI_SampleTimeFine	1060
Orientation Data		XDI_OrientationGroup	
	Quaternion	XDI_Quaternion	201y
	Rotation Matrix	XDI_RotationMatrix	202y
	Euler Angles	XDI_EulerAngles	203y
Acceleration		XDI_AccelerationGroup	
	Delta V (dv)	XDI_DeltaV	401y
	Acceleration	XDI_Acceleration	402y
	Free Acceleration	XDI_FreeAcceleration	403y
	AccelerationHR	XDI_AccelerationHR	404y
Angular Velocity		XDI_AngularVelocityGroup	
	Rate of Turn	XDI_RateOfTurn	802y
	Delta Q (dq)	XDI_DeltaQ	803y
	RateOfTurnHR	XDI_RateOfTurnHR	804y
Magnetic		XDI_MagneticGroup	
	Magnetic Field	XDI_MagneticField	C02y
Status		XDI_StatusGroup	
	Status Word	XDI_StatusWord	E020

y: The hex value of the Format bits (see table below). The value is formed by doing a bitwise OR of the available fields

⁷ XDA: Xsens Device API. Communication protocol in C, to be used on external processors.

Field	Format	Description	Short name
Precision			
	0x0	Single precision IEEE 32-bit floating point number	Float32
	0x1	Fixed point 12.20 32-bit number	Fp1220
	0x2	Fixed point 16.32 48-bit number	Fp1632
	0x3	Double precision IEEE 64-bit floating point number	Float64
Coordinate system			
	0x0	East-North-Up coordinate system	ENU
	0x4	North-East-Down coordinate system	NED
	0x8	North-West-Up	NWU

Example: the DataID for quaternions in NED coordinate system with fixed point 16.32 number format is represented as 0x2016.

7.3 MTData2

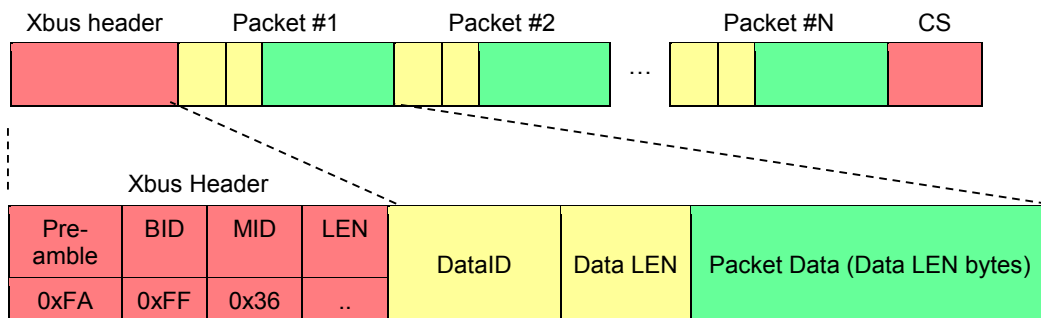
Data is represented in the MTData2 message.

MTData2

MID 54 (0x36)

DATA DATA (length variable)

The MTData2 message contains output data according the current OutputConfiguration. An MTData2 message consists of one or more packets, each containing a specific output. The layout of an MTData2 message is shown below:



An example data message is depicted below (explanation of the message, divided into parts, in the table):

FA FF 36 35 10 20 02 51 BC 10 60 04 00 21 49 AF 40 10 0C 39 B9 D8 00 B7 DD 80 00 3C C9 26 98 80 30 10 3F 80 00 01 B6 ED 60 01 36 94 A0 00 36 1E 60 00 E0 20 04 00 00 00 87 A0

Part of message (0x)	Meaning
FA FF 36 35	Xbus Header with total length of message (0x35)
10 20 02 51 BC	DataID 0x1020 (Packet counter), length 0x02, data (0x51 BC)
10 60 04 00 21 49 AF	DataID 0x1060 (Sample Time fine), length 0x04, data
40 10 0C 39 B9 D8 00 B7 DD 80 00 3C C9 26 98	DataID 0x4010 (velocity increment), length 0x0C, data
80 30 10 3F 80 00 01 B6 ED 60 01 36 94 A0 00 36 1E 60 00	DataID 0x8030 (orientation increment), length 0x10, data
E0 20 04 00 00 00 87	DataID 0xE020 (StatusWord), length 0x04, data
A0	Checksum

7.4 Synchronization and timing

The MTi 1-series modules can easily be synchronized with other sensors or sensor systems. The MTi accepts a pulse and can then transmit the latest available data. This SYNC_IN functionality does not influence the accuracy of the data as internally the MTi 1-series keeps estimating the orientation at its maximum frequency. Acceleration data and rate of turn data is also outputted with the shortest possible latency.

The Sync Settings are set with the SetSyncSettings message:

SetSyncSettings

MID 44 (0x2C)

DATA Setting List (N*12 bytes)

Set the synchronization settings of the device.

Settings

Each setting describes either a system event that should trigger a sync in event that should trigger a system action.

SYNC_IN setting

Offset (bytes)	Setting	Size (bytes)	Description
0	Function	1	Value 8: Send Latest
1	Line	1	Value 0 (SYNC_IN) or 6 (ReqData)
2	Polarity	1	Which line transition to respond to. One of: Rising Edge (1), Falling Edge (2) or Both (3)
3			Ignored for MTi 1-series
4	Skip First	2	The number of initial events to skip before taking action.
6	Skip Factor	2	The number of events to skip after taking the action before taking action again.
8			Ignored for MTi 1-series
10	Delay	2	Delay after receiving a sync pulse to taking action (100µs units, range [0..60000])

8 Magnetic interference

Magnetic interference can be a major source of error for the heading accuracy of any Attitude and Heading Reference System (AHRS). As an AHRS uses the magnetic field to reference the dead-reckoned orientation on the horizontal plane with respect to the (magnetic) North, a severe and prolonged distortion in that magnetic field will cause the magnetic reference to be inaccurate. The MTi 1-series module has several ways to cope with these distortions to minimize the effect on the estimated orientation.

8.1 Magnetic Field Mapping

When the distortion is deterministic, i.e. when the distortion moves with the MTi, the MTi can be calibrated for this distortion. These type of errors are usually referred to as soft and hard iron distortions. The Magnetic Field Mapping procedure compensates for both hard-iron and soft-iron distortions..

In short, the magnetic field mapping (calibration) is performed by moving the MTi together with the object/platform that is causing the distortion. The results are processed on an external computer (Windows or Linux), and the updated magnetic field calibration values are written to the non-volatile memory of the MTi 1-series module. The magnetic field mapping procedure is extensively documented in the Magnetic Field Mapper User Manual (MT0202P), available in the MT Software Suite.

8.2 Active Heading Stabilization (AHS)

It is often not possible or desirable to connect the MTi 1-series module to a high-level processor/host system, so that the Magnetic Field Mapping procedure is not an option. Also, when the distortion is non-deterministic the Magnetic Field Mapping procedure does not yield the desired result. For all these situations, the on-board XKF3 sensor fusion algorithm has integrated an algorithm called Active Heading Stabilization (AHS).

The AHS algorithm delivers excellent heading tracking accuracy. Heading tracking drift in the MTi 1-series can be as low as 1 deg per hour, while being fully immune to magnetic distortions.

AHS is available in all filter profiles. AHS is off by default from firmware version 1.0.18. To enable AHS, enable AHS with SetOptionFlags (see the Low Level Communication Protocol Documentation). The message for enabling AHS is FA FF 48 08 00 00 00 10 00 00 00 00 A1. Alternatively, enabling AHS can be done in MT Manager 4.6.3 and higher.

9 Package and handling

Note that this is a mechanical shock (g) sensitive device. Proper handling is required to prevent damage to the part.
Note that this is an ESD-sensitive device. Proper handling is required to prevent damage to the part.

Make sure not to apply force on the components of the MTi 1-series module, especially when placing the MTi 1-series module in an IC-socket.

9.1 Package drawing

The MTi 1-series module is compatible with JEDEC PLCC28 IC-sockets.

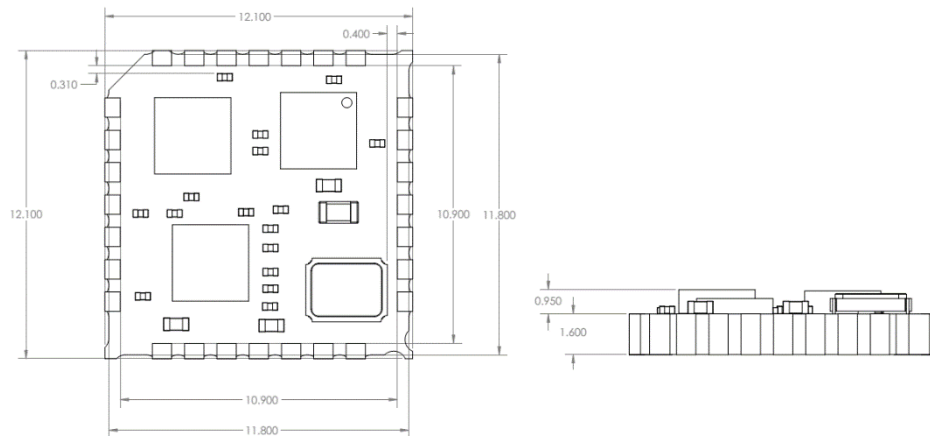


Figure 18: General tolerances are +/- 0.1 mm

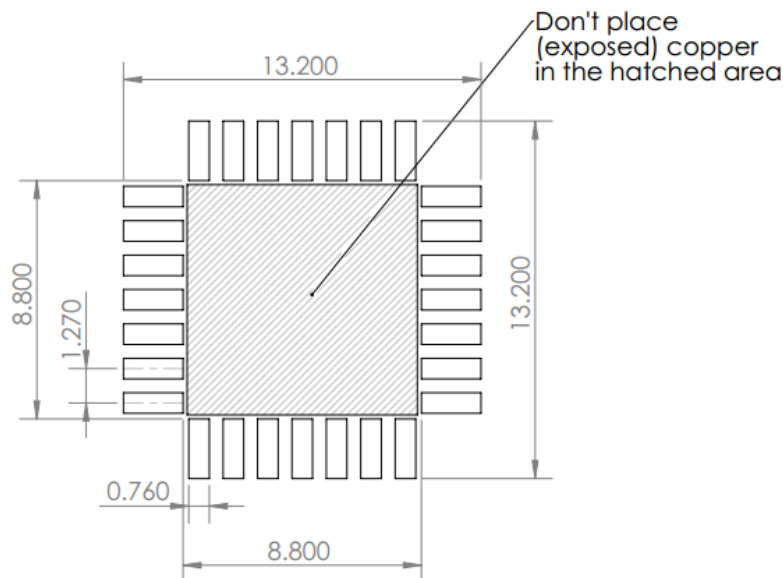


Figure 19: Recommended MTi 1-series module footprint

9.2 Mounting considerations

The module contains a MEMS (Micro Electro Mechanical System) chip and is therefore sensitive for stress applied on the PCB. To minimize stress apply the following design rules for the PCB and housing.

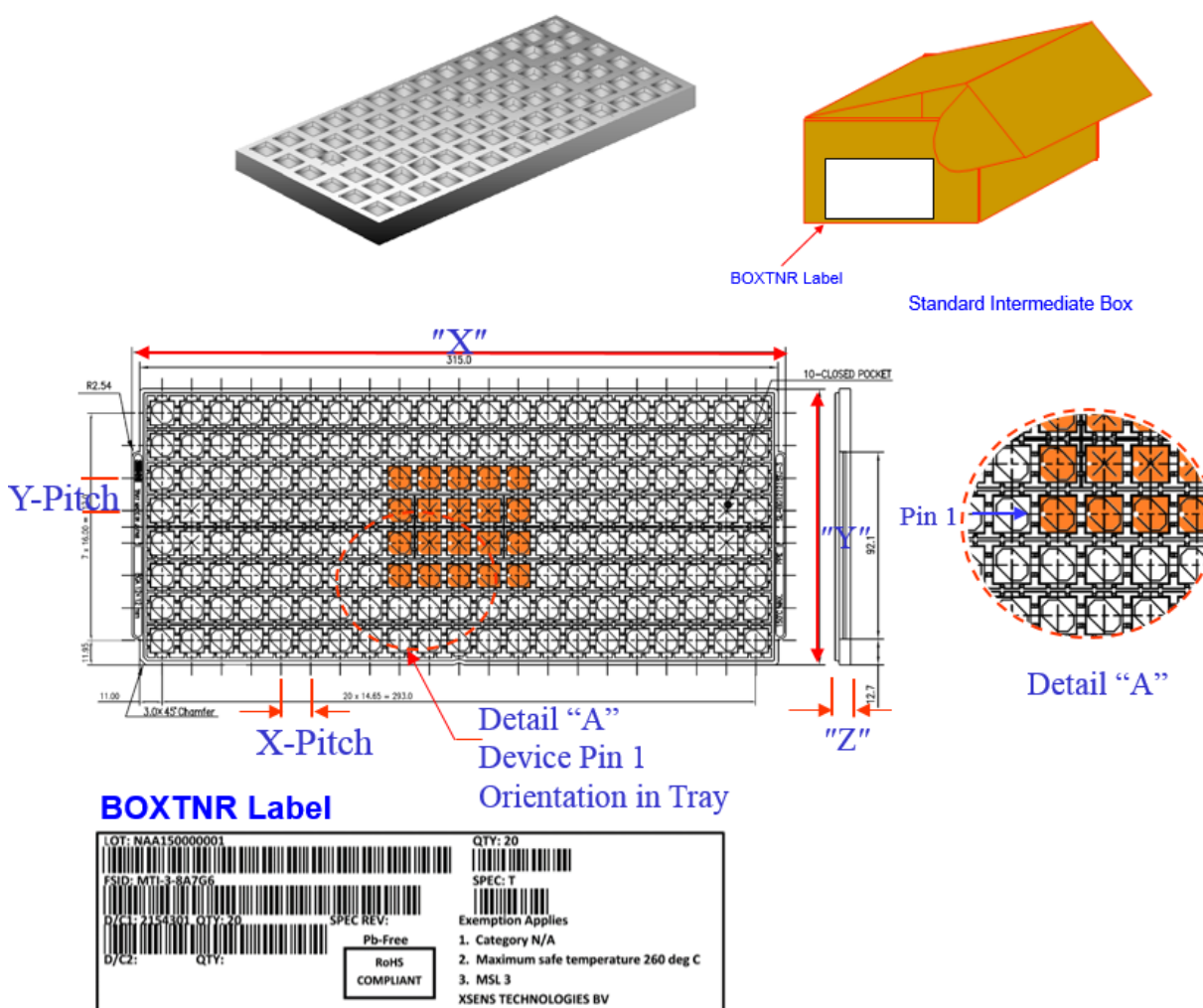
Avoid stress on the PCB by screwing/mounting it in a housing, applying unequal or excessive forces to the mounting positions. Ideally the PCB should be mounted using mechanical dampeners.

- Avoid force applied on the PCB by push buttons, connectors etc. close to the MTi-1 series module.
- Avoid heat sources close to the MTi-1 series
- Avoid vibrations caused by speaker, buzzer etc.

9.3 Packaging

The MTi 1-series module is shipped in trays with 20 modules or in reels with 250 modules.

9.3.1 Tray packaging information

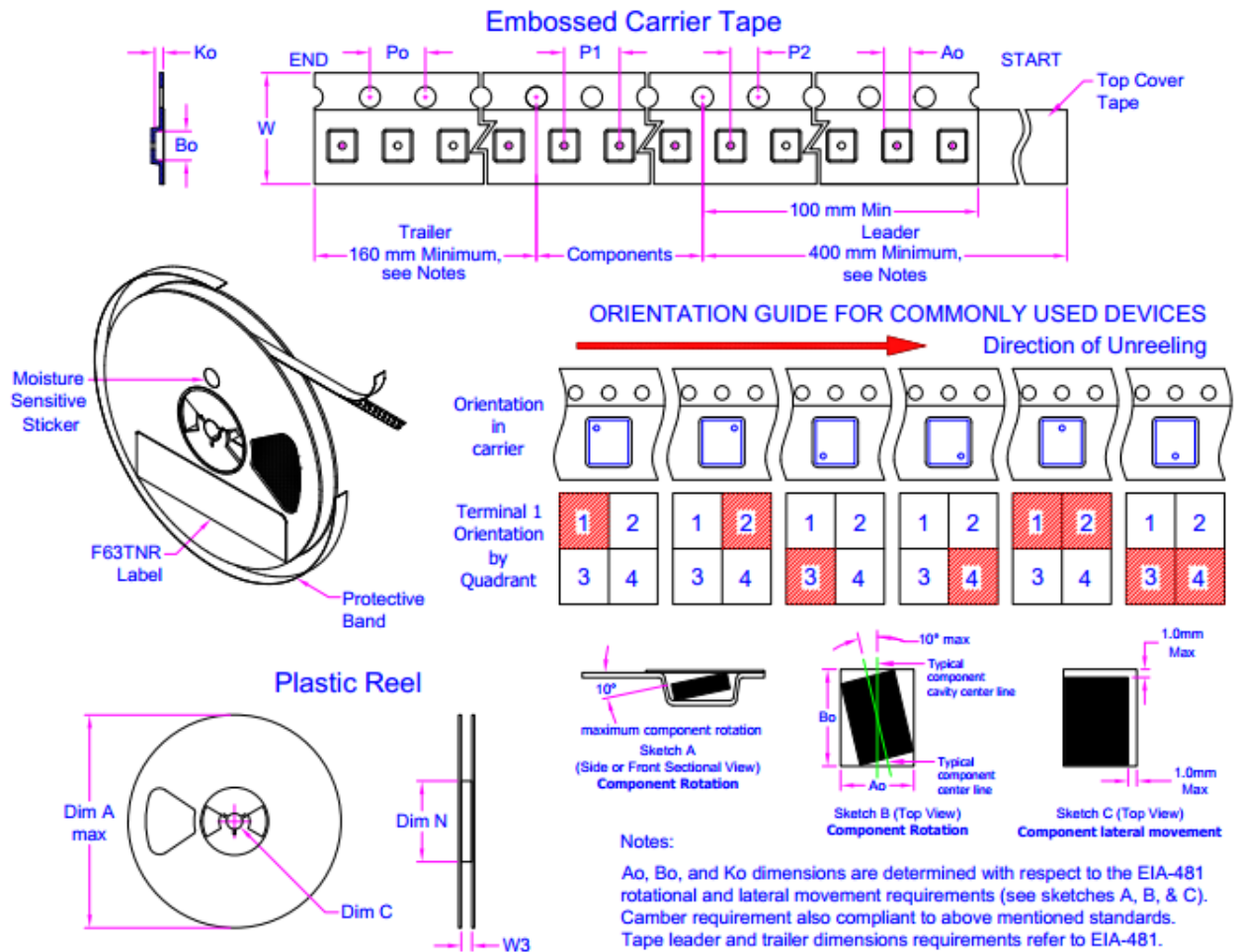


Tray Dimensions (mm)						Tray packaging information		Pin 1
Length "X"	Width "Y"	Height "Z"	Pocket X-Pitch	Pocket Y-Pitch	Pocket X-Y Array	Qty/Tray	Qty/Box	
322.60	135.90	7.62	14.65	16.00	12 x 12	20 units	20 units	Detail "A" Marking

NOTES:

- All dimensions are in millimeters
- Pictured tray representative only, actual tray may look different.

9.3.2 Reel packaging information



F63TNR LABEL

LOT: NAA150000001	QTY: 250
PID: MTI-3-8A7G6	SPEC: R
D/C: 2154301	QTY: 250
SPEC REV:	Exemption Applies
Pb-Free	1. Category N/A
RoHS COMPLIANT	2. Maximum safe temperature 260 deg C
	3. MSL 3
	XSENS TECHNOLOGIES BV

Carrier tape (mm)							Reels (mm)				Pin 1	Packing
Ao	Bo	Ko	W	Po	P1	P2	A	N	C	W3	Orientation by quadrant	QTY/ Reel
12.6	12.6	2.9	23.70	3.90	15.90	1.90	177.80	55	12.80	23.90	1 & 2	250
-	-	-	-	-	-	-	-	-	-	-	-	-
12.8	12.8	3.10	24.30	4.10	16.10	2.10	-	-	13.50	27.40	-	-

NOTES:

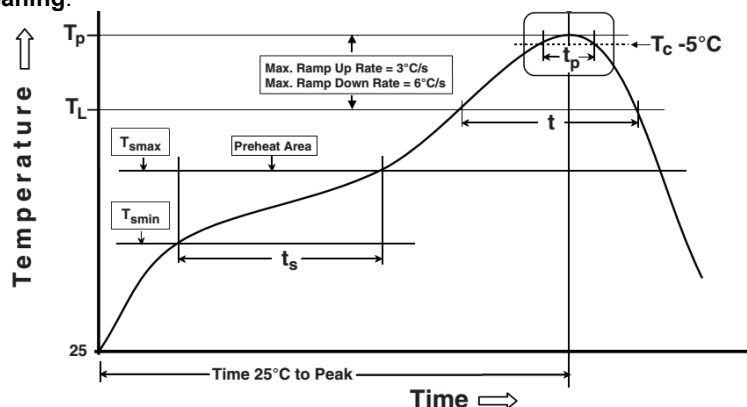
- All dimensions are in millimeters, unless otherwise specified

9.4 Reflow specification

The moisture sensitivity level of the MTi 1-series modules corresponds to JEDEC MSL Level 3, see also:

- IPC/JEDEC J-STD-020E "Joint Industry Standard: Moisture/Reflow Sensitivity Classification for non-hermetic Solid State Surface Mount Devices"
- IPC/JEDEC J-STD-033C "Joint Industry Standard: Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices".

The sensor fulfils the lead-free soldering requirements of the above-mentioned IPC/JEDEC standard, i.e. reflow soldering with a peak temperature up to 260°C. Recommended Preheat Area (t_s) is 80-100 sec. The minimum height of the solder after reflow shall be at least 50µm. This is required for good mechanical decoupling between the MTi 1-series module and the printed circuit board (PCB) it is mounted on. Assembled PCB's may **NOT** be cleaned with **ultrasonic cleaning**.



IPC-020e-5-1

10 Trademarks and revisions

10.1 Trademarks

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10.2 Revisions

Revision	Date	By	Changes
A	8 Jul 2015	MHA	Initial release
B	12 Dec 2015	MHA	• Added I²C, SPI interfaces • Rotated modules in tray • Added mounting considerations • Corrected ADD0 pin in pin map • Changed description for nRST pin • Corrected notes on R_{PSEL} • Added packaging information • Added reels • Ordering code adapted • Added RateOfTurnHR and AccelerationHR outputs
B1	4 May 2016	MHA	• Added MTBF • Corrected bias specification for accel/gyro
C	11 Aug 2016	MHA	• Corrected full range of mag • AHS off by default in FW 1.0.18
C1	7 Sep 2016	MHA	• Added VDD noise requirements • Updated list of filter profiles • Corrected typical application schematic